

AMENDMENTS TO THE CLAIMS**In the Claims:**

The following listing of claims replaces all prior versions and listings of claims in the application.

Listing of Claims:

1. (Withdrawn – Original) A wafer half-shell having a mouth delimited by at least one annular surface and one or more side walls, in which the mouth annular surface and the surfaces of the side wall have a substantially smooth surface finish, wherein the outer surface of the side wall has a porous, continuous or discontinuous region which extends peripherally and is receded relative to the mouth annular surface of the half-shell.

2. (Withdrawn – Original) A half-shell according to Claim 1, wherein the porous region is the surface resulting from the cutting of one or more radial walls connected to the side wall of the half-shell in a receded position relative to the annular surface defining the mouth of the half-shell.

3. (Withdrawn – Original) A half-shell according to Claim 2, obtained by cutting from an intermediate wafer comprising a plurality of half-shells interconnected by at least one interconnecting wall extending from the side wall of each half-shell and connected to the half-shells in a receded position relative to the annular mouth surface.

4. (Withdrawn – Original) A half-shell according to Claim 1, wherein said annular surface comprises centering means adapted to fit with complementary centering means of a complementary half-shell.

5. (Withdrawn – Original) A half-shell according to Claim 4, wherein said centering means comprise tapered annular coupling surfaces or coupling surfaces having a U, V, L-shaped profile or a toothed, Greek-key pattern or zigzag profile.

6. (Withdrawn – Original) A wafer comprising a plurality of half-shells with at least one containing side wall and interconnected by at least one interconnecting wall, wherein the

interconnecting wall is connected to the half-shells in a receded position relative to the annular mouth surface of each half-shell.

7. (Withdrawn – Original) A wafer according to Claim 6, wherein the half-shells are interconnected by means of a plurality of interconnecting walls (8a, 8b) which extend from the containing side walls (10) of the half-shells.

8. (Original) A food product comprising a half-shell according to Claim 1 and including a mass of filling contained in the half-shell.

9. (Previously presented) A food product according to Claim 8, comprising a pair of half-shells, fitted together mouth to mouth and including a mass of filling, wherein at least one of the half-shells is a wafer half-shell having a mouth delimited by at least one annular surface and one or more side walls, in which the mouth annular surface and the surfaces of the side wall have a substantially smooth surface finish, wherein the outer surface of the side wall has a porous, continuous or discontinuous region which extends peripherally and is receded relative to the mouth annular surface of the half-shell.

10. (Original) A food product comprising at least two wafer half-shells coupled one to the other along annular mating surfaces defining their mouth profile, wherein said annular mating surfaces of each of said half-shells have centering means complementary one to the other.

11. (Original) A food product according to Claim 10, wherein said centering means comprise formations susceptible of mutual engagement.

12. (Previously presented) A food product according to Claim 10, wherein said centering means comprise annular mating surfaces having a toothed profile, a U-shaped profile, a V-shaped profile, a L-shaped profile, a Greek-key pattern profile or a zigzag profile.

13. (Previously presented) A food product according to Claim 10, wherein said centering means comprise tapered annular mating surfaces.

14. (Original) A food product according to Claim 10, wherein at least one of said half-shells has a sidewall with a porous, continuous or discontinuous region extending peripherally, which is receded relative to the mating annular surface of said half-shell.

15. (Original) A food product according to claim 10, wherein said annular mating surfaces and the surface of said centering means have a smooth surface finish.

16. (Withdrawn – Original) A method for the preparation of a wafer half-shell with a mouth and a containing side wall, comprising the steps of:

- preparing a wafer comprising a plurality of the half-shells connected by at least one interconnecting wall connected to the half-shells in a recessed position relative to the annular mouth surface of the half-shells, and

- separating the individual half-shells from the interconnecting wall by cutting in a direction perpendicular to the general plane of the interconnecting wall.

17. (Withdrawn – Currently amended) A method according to Claim [[15]] 16, wherein the wafer is a product produced by baking a wafer batter in a mould.